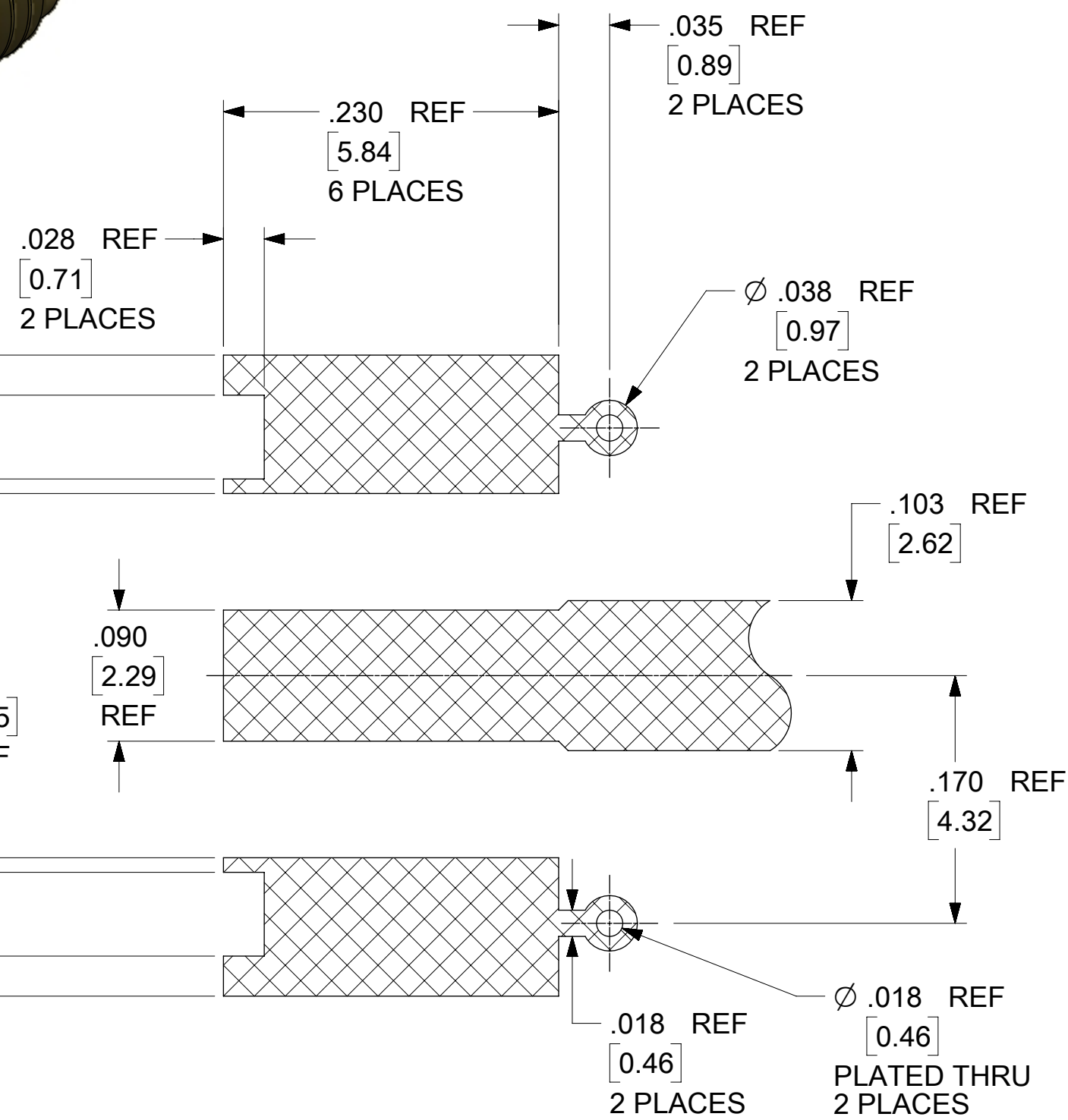
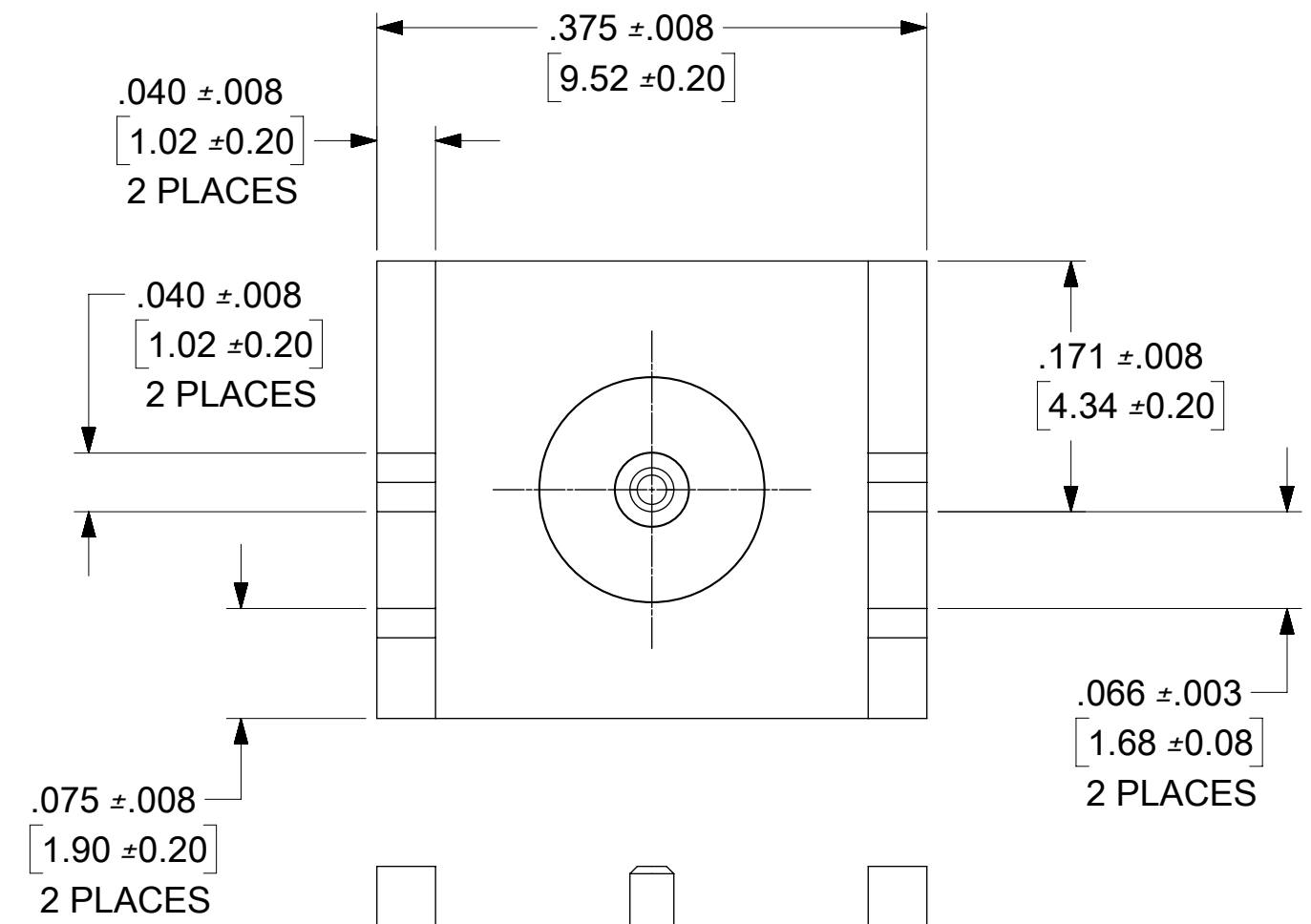
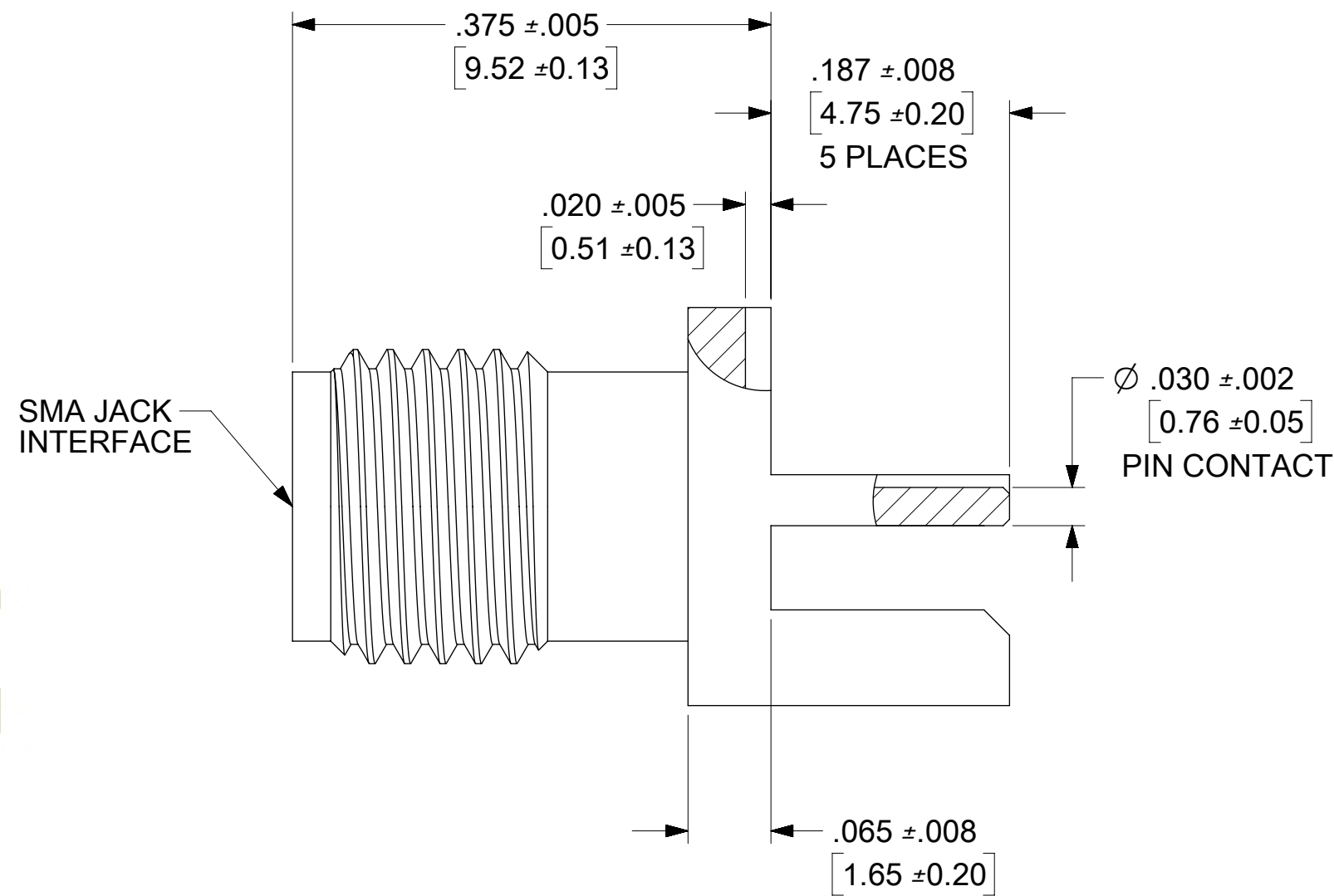
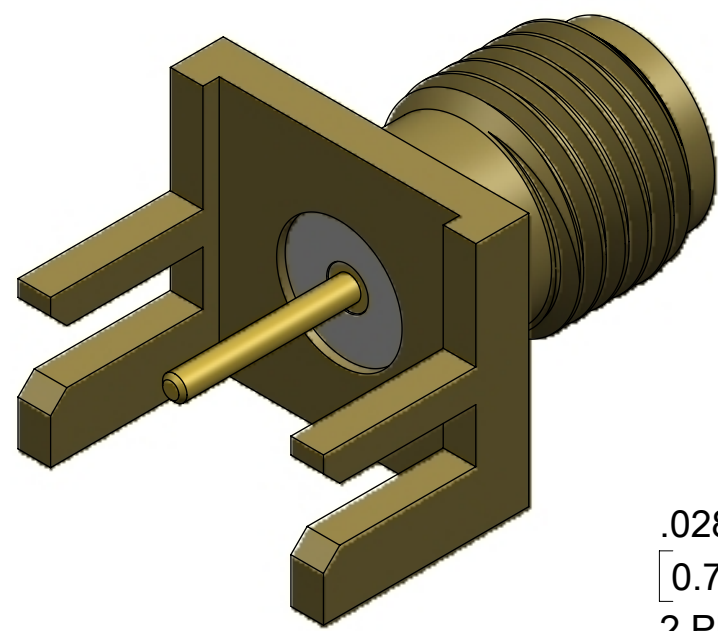
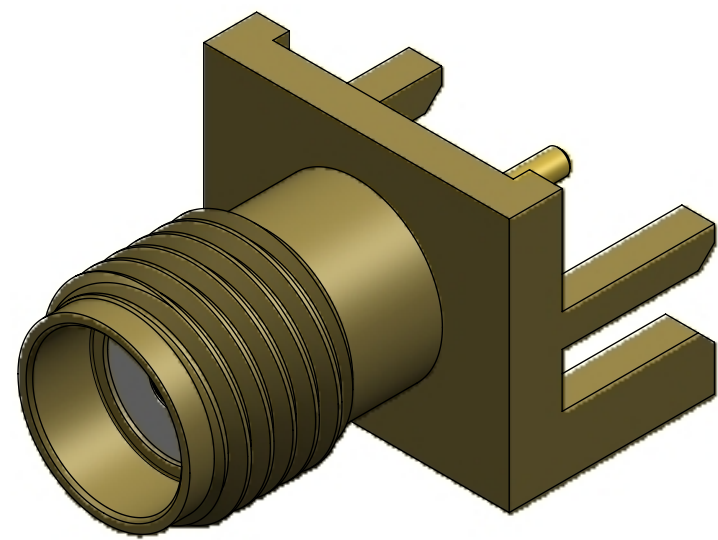


MATERIALS AND FINISHES

**BODY: BRASS
PLATED GOLD (SEE TABLE)**

**CENTER CONTACT: BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)**

INSULATOR: PTFE



PCB PAD (FOR REFERENCE ONLY)

BOARD THICKNESS: .062 [1.57]
BOARD MATERIAL: FR4 WITH 1.0 OZ (28 g) COPPER ON BOTTOM (GROUND) SIDE

73251-1153	GOLD (1μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (5μ-in MIN) OVER NICKEL (50μ-in MIN)	TRAY (80 PIECES)
73251-1152	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	TRAY (20 PIECES)
73251-1151	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	ONE 73251-1150 PER BAG
73251-1150	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	TRAY (80 PIECES)

PART NO.	BODY	CONTACT	DESCRIPTION
	PLATING		PACKAGING

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SYMBOLS: ∇ = 0, ∇ = 0, ∇ = 0, ∇ = 0, ∇ = 0, ∇ = 0, ∇ = 0, ∇ = 0, ∇ = 0, ∇ = 0

DIMENSION UNITS: INCH, NTS

SCALE: INCH, NTS

GENERAL TOLERANCES (UNLESS SPECIFIED):

	MM	INCH
4 PLACES ±		±
3 PLACES ±		± 0.005
2 PLACES ±	0.13	± 0.01
1 PLACE ±	0.25	±
0 PLACES ±		±
ANGULAR TOL	± 2.0°	

EC NO: 172847
DRWN: LMEIER 2018/02/23
CHK'D: SSSHAH 2018/03/01
APPR: AROBERTSON 2018/03/01

INITIAL REVISION:
DRWN: TEF 2002/06/27
APPR: GMH 2002/06/27

THIRD ANGLE PROJECTION

DRAWING: C-SIZE, SERIES: 73251

MOLEX logo

SMA JACK, EDGE MOUNT
50 OHMS, EWR-11795 SMA-J/PCB

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER: SD-73251-115, DOC TYPE: PSD, DOC PART: 001, REVISION: B1

MATERIAL NUMBER: SEE TABLE, CUSTOMER: SEE TABLE, SHEET NUMBER: 1 OF 1

PS-89675-3460	PRODUCT SPECIFICATION
MIL-STD-348B, FIG. 310-2	INTERFACE
SPECIFICATION	DESCRIPTION
DOCUMENT STATUS: P1	RELEASE DATE: 2018/03/01 20:38:20